Features

- Frequency:1-20GHz
- Insertion Loss: 0.4dB（typ.)
- Limit Power:16dBm
- Tolerance Power:37dBm(CW)
- Input/Output: 50Ω
- Die Size: 1.42x0.81x 0.1 mm

Typical Applications

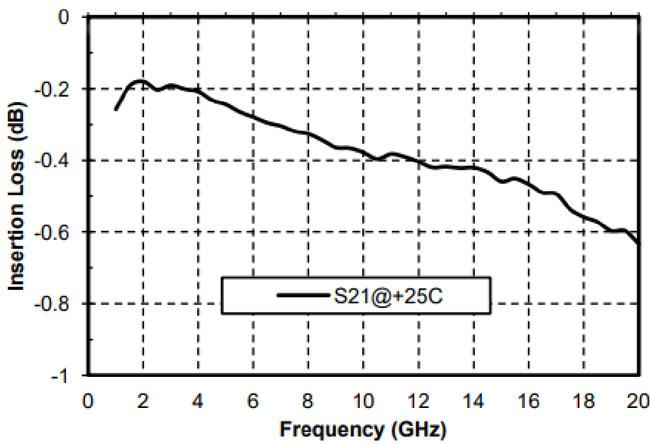
- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- Fiber Optics

Electrical Specifications

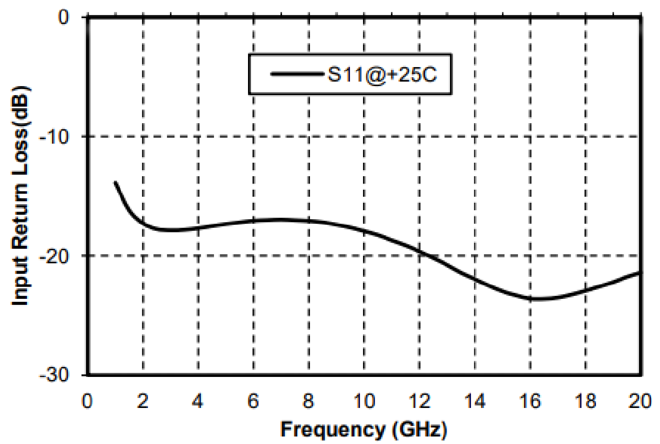
TA = +25ºC

Parameters	Min.	Typ.	Max.	Units
Frequency		1-20		GHz
Insertion Loss	-	0.4	-	dB
Input Return Loss	-	19	-	dB
Output Return Loss	-	18	-	dB
Limit Power	-	16	-	dBm
Tolerance Power		37		dBm

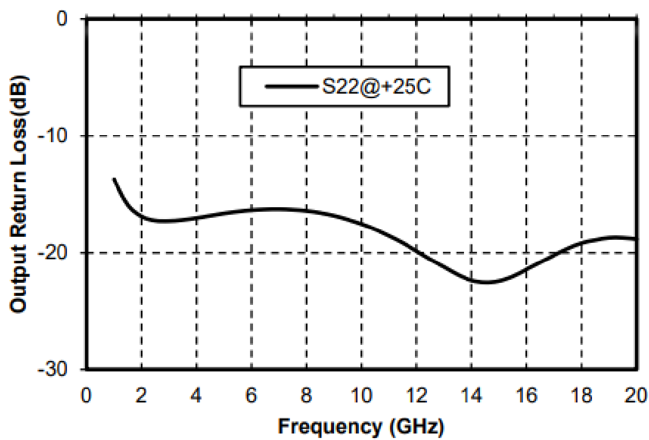
Insertion Loss Vs. Frequency



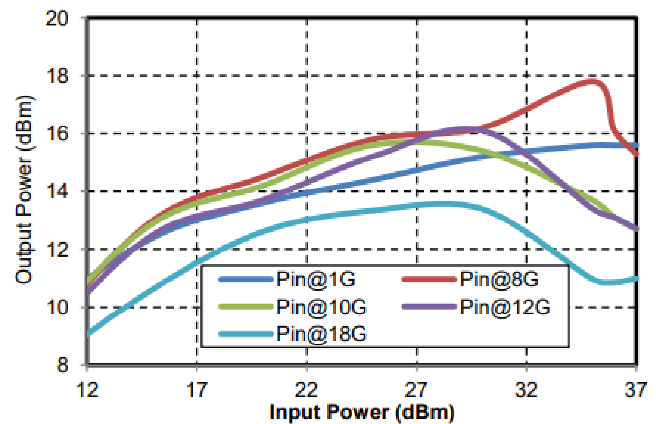
Input Return Loss Vs. Frequency



Output Return Loss Vs. Frequency



Limit Power @1G、8G、10G、12G&18G



Outline Drawing:

All Dimensions in um, tolerance range ±50um

Pad Description

PAD	Function	Description
1	RF COMM	RF signal input, No DC blocking capacitor， external DC-blocking capacitor required
2	RF OUTPUT	RF signal output, with DC blocking capacitor
Die Bottom	GND	Die bottom must be connected to RF/DC ground.

Assembly Drawing

Notes:
1. Die thickness: 100um
2. Typical bond pad is 100*100 μm^2
3. Bond pad metalization: Gold
4. Backside metalization: Gold
5. Backside of the die (GND)
6. No connection required for unlabeled bond pads

Maximum Ratings:
1.RF input power：+37dBm
2.Storage temperature: -65℃ to +150℃
3. Operating temperature: -55℃ to 125℃